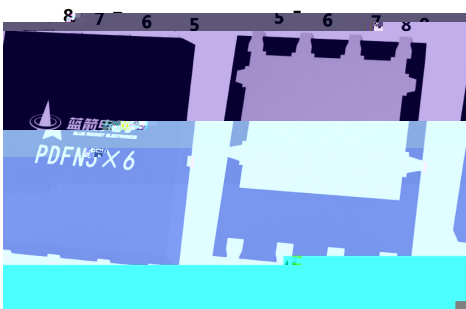
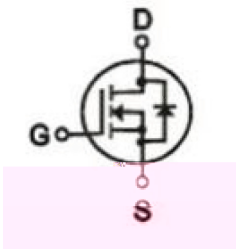


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[illegible]

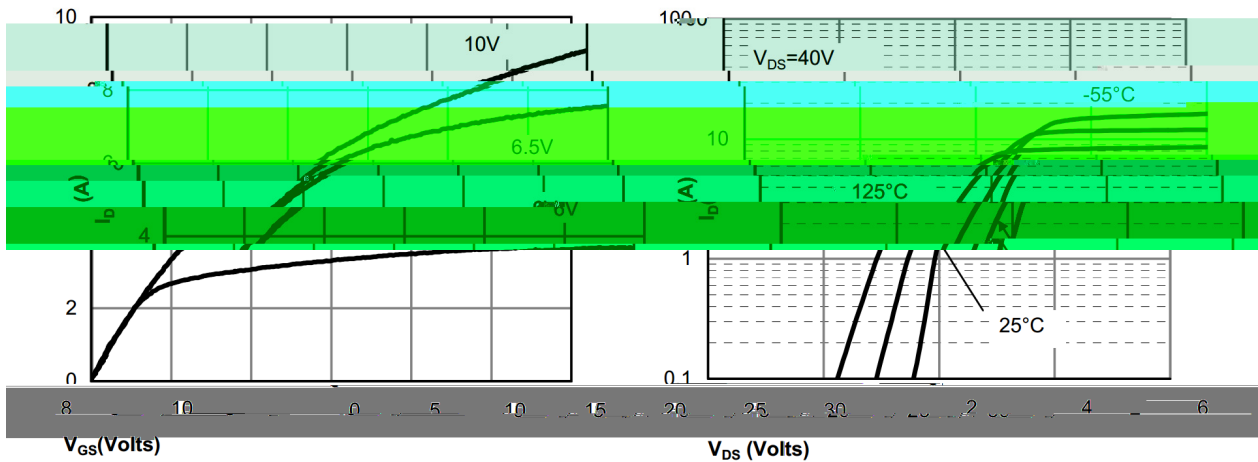


Figure 2: Transfer Characteristics

Figure 1: On-Region Characteristics

Figure

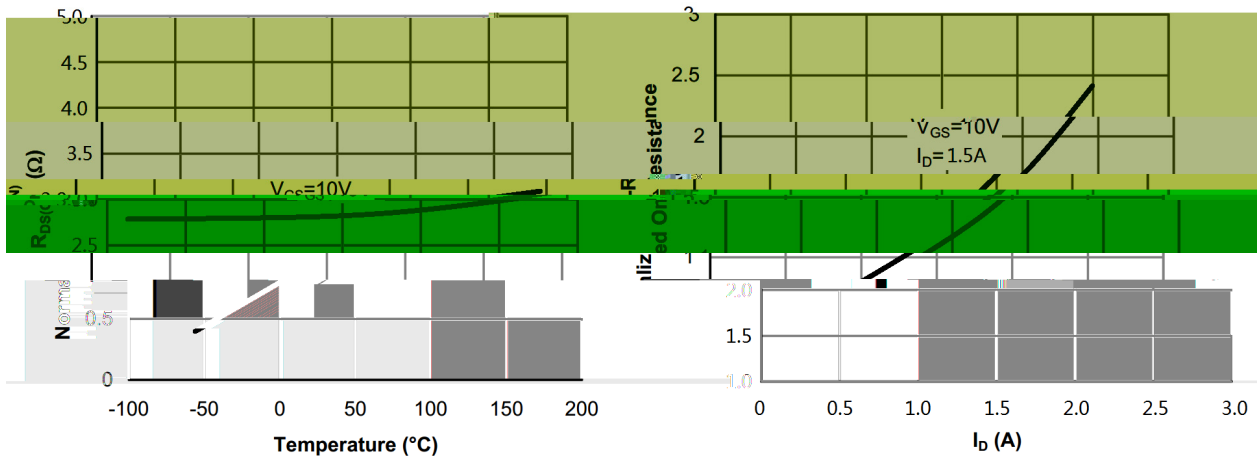


Figure 4: On-Resistance vs. Drain Current and Temperature

Figure 3: On-Resistance vs. Drain Current and

Gate Voltage

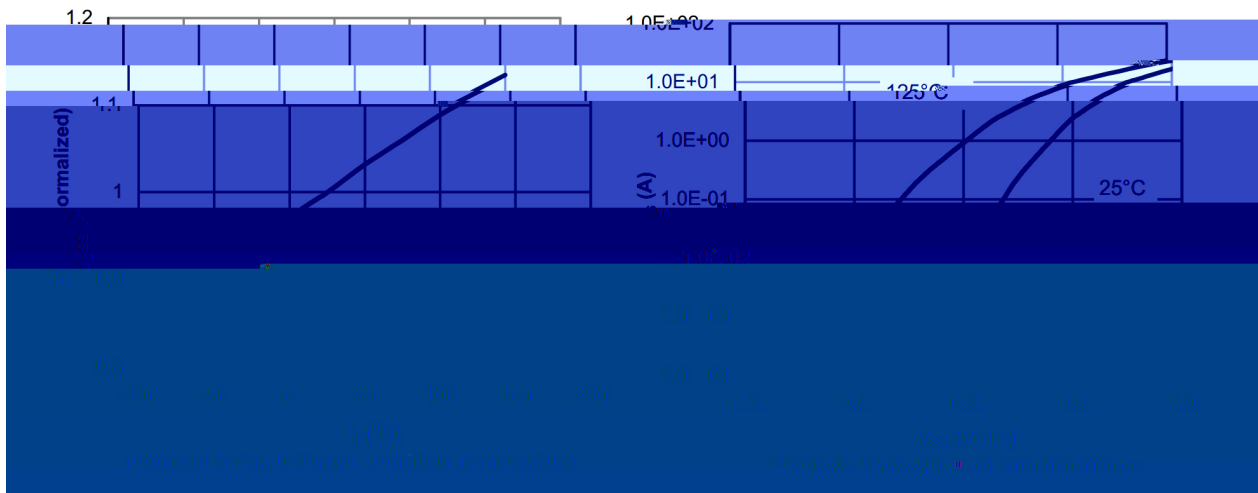


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

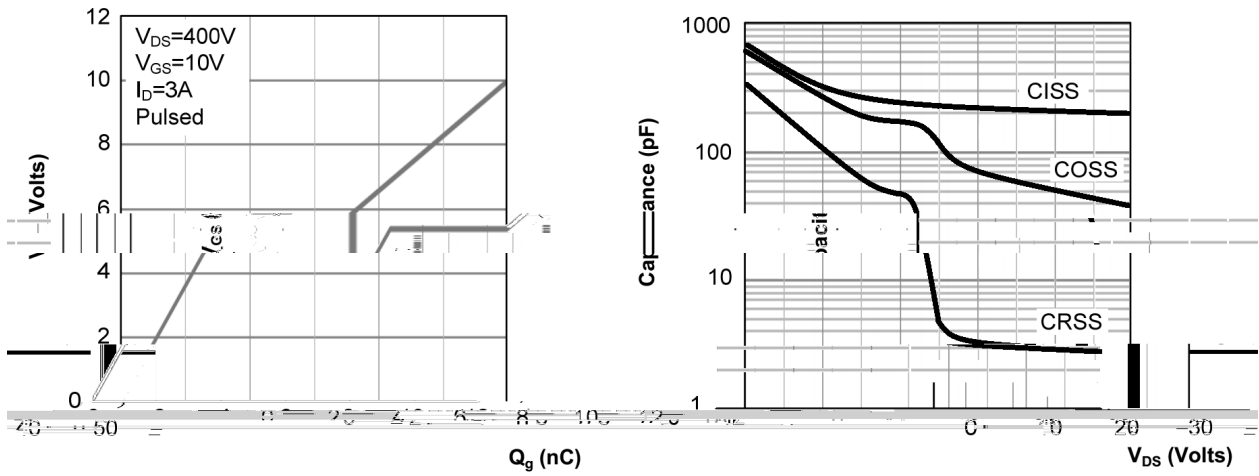


Figure 7: Gate-Charge Characteristics

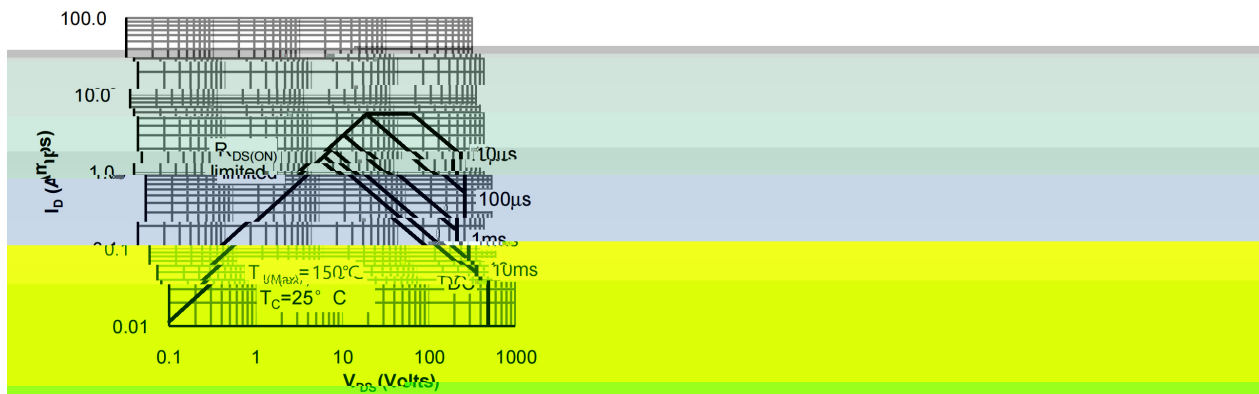


Figure 9: Maximum Forward Biased Safe Operating Area

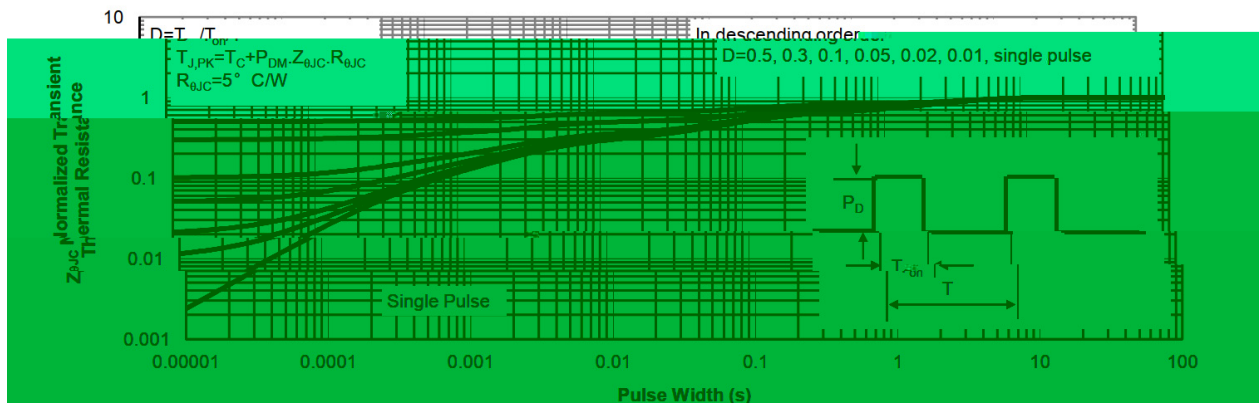
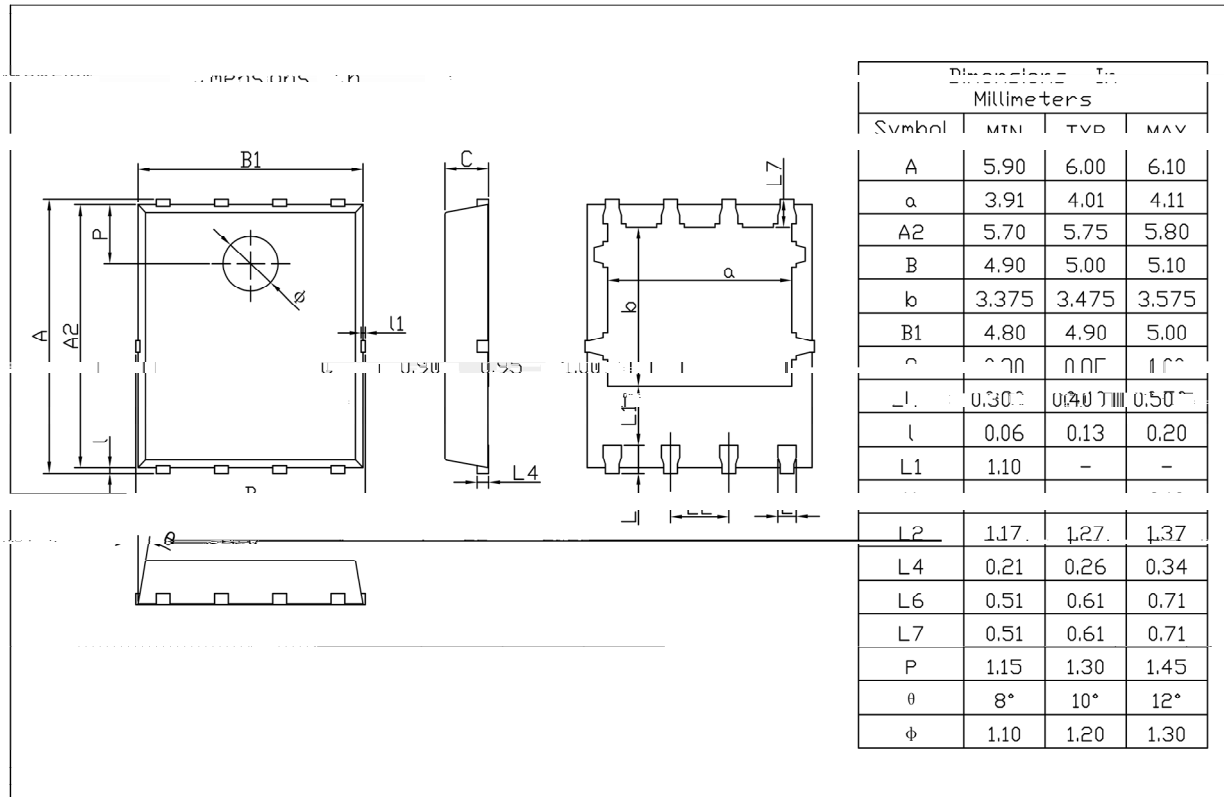


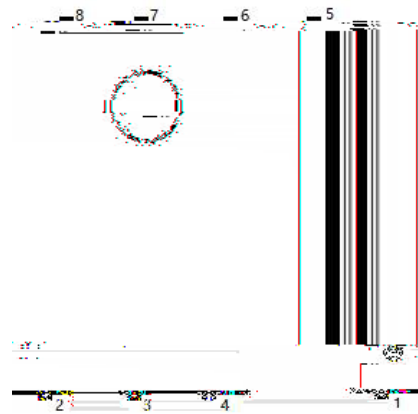
Figure 10: Normalized Maximum Transient Thermal Impedance

PDFN5 X6

Unit:mm

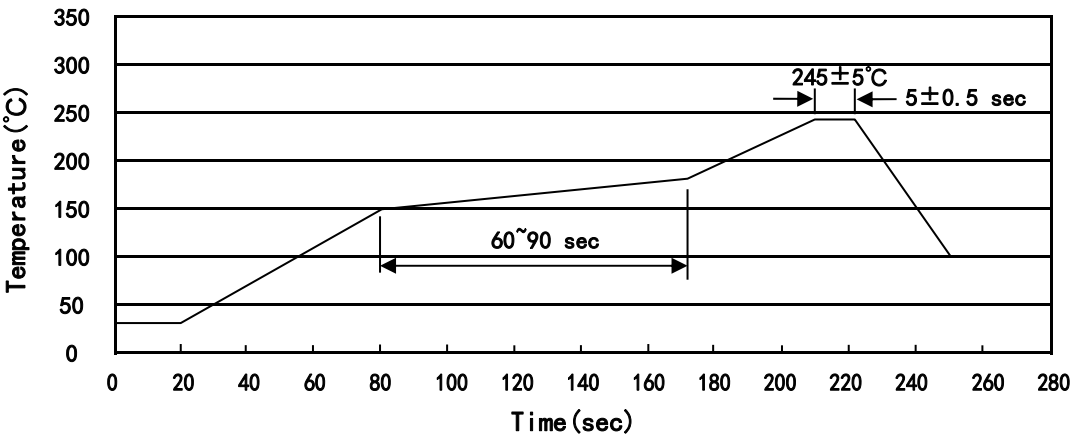


Rev.01 202209



BR

Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

± ±

	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box